

AirBorn, Inc.
Product Technical Bulletin #2 (PTB2)
AirBorn W and R series

TIN LEAD (SnPb) SOLDER DIP SPECIFICATION SUMMARY

Application: AirBorn W and R series solder dip terminations.

Gold Plated Terminations:

1. Sample Size: 13 Connectors, 13 pins on each (per ANSI/ASQC Z1.4, Level S-2, 1% AQL).
2. Pre-conditioning: 8 hours steam age, before solder coating.
3. Solder Coating: Per J-STD-006: MIL-STD-202, Method 208, J-STD-001
4. Acceptance Criteria: 95% coverage per MIL-STD-202, Method 208, J-STD-001
5. Shelf-Life Capability Projection: Indefinite, assuming normal temperature, humidity and non-contaminant environment.

Hot Solder Dipped Terminations:

1. Solderability and steamage to be performed after dipping (at customer request).
2. Hot solder dip process utilizing solder per J-STD-006.
3. Post-Dip Inspection:
 - a. Sample Size: 13 connectors, 13 pins on each (per ANSI/ASQC Z1.4, Level S-2, 1% AQL).
 - b. Acceptance Criteria: 95% coverage per MIL-STD-202, Method 208, J-STD-001
4. Shelf-Life Capability Projection: 1 – 2 years, assuming normal temperature, humidity and non-contaminant environment.

Lead-free solder (SAC305) is also available upon request.